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## COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

## A PROCESS FOR FORMING A CONDUCTING STRUCTURE LAYER THAT CAN REDUCE METAL ETCHING RESIDUE

the	specification of which	ı			
_X 	is attached hereto. was filed on as Application Seria		and was amended on		<u> </u>
app app app	cification, including the I acknowledge the lication in accordanc I hereby claim fore lication(s) for patent of	ne claims, as amended duty to disclose info e with Title 37, Code of ign priority benefits un or inventor's certificate inventor's certificate has	nd understand the content of by any amendment referred rmation which is material to of Federal Regulations, § 1.5 der Title 35, Untied States C elisted below and have also in aving a filing date before that	i to above. the patenta 6(a). ode, §119 dentified belo	ability of this of any foreign ow any foreign
	Number	Country	Date Filed(yyyy/mm/dd)	Yes	No
	89115000	Taiwan, R.O.C.	2000/7/27	X	
traı	nsact all business in t Jiawei Huang		6) Chanette Armstrong	ith: (Reg. No.	39,081) 44,011)
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

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